TDS

深圳市优阳科技有限公司

Technical Data Sheet

EAP-6S

oligomer · monomer · photoinitiator· additive

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EAP-6S Cationic Thermal Stabilizer

MW: 225

Density, g/cm³: 1.02

Dosage: 0.1–0.2%

Appearance: Transparent liquid

Viscosity at 25°C: 50 cps

EAP-6S is an excellent thermal blocking agent with good compatibility and low dosage. It provides long-lasting stability for the room-temperature storage issues associated with cationic thermal initiation. Without the addition of a thermal blocking agent, adhesives can only be stored at room temperature for 2 - 7 days (depending on the activity of the base resin), after which the viscosity will increase significantly or even gel and cure. Cold-chain storage and transportation are usually required throughout. After adding EAP-6S thermal blocking agent, the product can be stored stably for 3 - 6 months at ambient temperatures not exceeding 40° C, with viscosity increasing by only <10%. When used together with CTI-100 cationic thermal initiator, the deblocking temperature is increased from the original 80° C to 90° C, enabling rapid reaction and curing without affecting the physical and chemical properties of the cured film.